广东盈骅新材料科技有限公司
GUANGDONG HINNO-TECH CO.,LTD.

Y-207HS & Y-207HSP

High Tg ,Low CTE Laminate&Prepreg for IC Packages

产品特点:

●低膨胀、低收缩， 有效降低 IC 封装基板翘曲

●高模量(高弹性率)

●优异的耐热性

●无卤、高 Tg230℃

●优异的厚度均匀性

应用领域:

CSP、BGA、FC-PKG 等封装用基板。

Key Features:

●Low CTE and low shrinkage, effective to reduced the warpage of substrate for IC PKG

●High modulus,

●Excellent heat resistance

●Halogen-free and Tg230℃

●Excellent uniformity of thickness

Applications:

Substrates for CSP 、BGA 、FC-PKG etc.

1、General properties

Property	Item	IPC-TM-650	Test Condition	Units	Typical value
热性能 Thermal	玻璃化转变温度 Glass Transition Temperature	2.4.24.4	DMA	℃	230
		2.4.24.5	TMA	℃	210
	X,Y 轴方向膨胀系数 X,Y-CTE	2.4.24.5	＜Tg	ppm/℃	12～14
			＞Tg	ppm/℃	4～7
	288℃分层时间 T288	2.4.24.1	Etched	min	＞60
	288℃热冲击 Thermal stress	2.6.8	288℃， solder dip	S	＞300
	热失重(weight loss 5%) Decomposition temperature	2.4.24.6	TGA	℃	405
电性能 Electrical	体积电阻 Volume Resistivity	2.5.17.1	C-96/35/90	MΩ-cm	$>10^8$
	表面电阻 Surface Resistivity	2.5.17.1	C-96/35/90	MΩ	$>10^8$
	Dk (RC50%)	2.5.5.9	1GHz;C-24/23/50	-	4.5
	Df (RC50%)	2.5.5.9	1GHz;C-24/23/50	-	0.008
	弯曲强度 Flexural Strength LW	2.4.4	A	MPa	500
	弯曲强度 Flexural Strength CW				460
	弯曲模量 Flexural modulus	JB/T 6544- 1993	A	GPa	30

物理性能 Physical	杨氏模量 Young's Modulus	GB/T 2015-91	A	GPa	28
	剥离强度 Peel Strength (Hoz Copper Foil)	2.4.8	288℃/10s	lb/inch	5.5
	热导率 Thermal conductivity	ASTM-D5470	C-96/35/90	W/(m*k)	0.68
	吸水率 Moisture Absorption	2.6.2.1	D-24/23	%	0.15
	阻燃等级 Flammability	UL94	UL94	-	V0

Specimen thickness：0.4mm or 0.8mm. Test Method is according to IPC TM-650 or National Standard Test Method.